

Features

- Low On-Resistance:
 - 3.0 Ω @ 4.5V
 - 4.0 Ω @ 2.5V
 - 6.0 Ω @ 1.8V
 - 10 Ω @ 1.5V
- Very Low Gate Threshold Voltage, 1.0V max
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- ESD Protected Gate
- Lead, Halogen, and Antimony Free By Design/RoHS Compliant (Note 2)**
- "Green" Device (Note 3)**
- Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

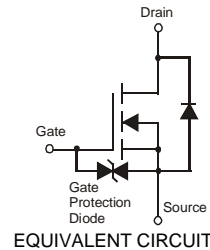
- Case: SOT-523
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.002 grams (approximate)



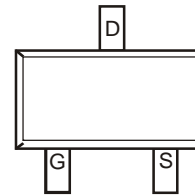
ESD PROTECTED



TOP VIEW



EQUIVALENT CIRCUIT



TOP VIEW

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain Source Voltage	V_{DSS}	20	V
Gate-Source Voltage	V_{GSS}	± 10	V
Drain Current (Note 1)	I_D	230	mA
Pulsed Drain Current	I_{DM}	805	mA
	$T_P = 10\mu\text{s}$		

Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Total Power Dissipation (Note 1)	P_D	300	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

- Notes:
- Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 - No purposefully added lead.
 - Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 4)						
Drain-Source Breakdown Voltage	BV_{DSS}	20	—	—	V	$V_{GS} = 0V, I_D = 100\mu A$
Zero Gate Voltage Drain Current @ $T_C = 25^\circ\text{C}$	I_{DSS}	—	—	500	nA	$V_{DS} = 20V, V_{GS} = 0V$
Gate-Body Leakage	I_{GSS}	—	—	± 1	μA	$V_{GS} = \pm 10V, V_{DS} = 0V$
				± 500	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$
				± 100	nA	$V_{GS} = \pm 5V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 4)						
Gate Threshold Voltage	$V_{GS(th)}$	0.5	—	1.0	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	1.8	3.0	Ω	$V_{GS} = 4.5V, I_D = 100mA$
		—	2.4	4.0		$V_{GS} = 2.5V, I_D = 50mA$
		—	2.9	6.0		$V_{GS} = 1.8V, I_D = 20mA$
		—	3.7	10.0		$V_{GS} = 1.5V, I_D = 10mA$
		—	5.4	15.0		$V_{GS} = 1.2V, I_D = 1mA$
Forward Transconductance	$ Y_{fs} $	—	242	—	mS	$V_{DS} = 10V, I_D = 0.1A$
Source-Drain Diode Forward Voltage	V_{SD}	0.5	—	1.0	V	$V_{GS} = 0V, I_S = 115mA$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{iss}	—	14.1	—	pF	$V_{DS} = 15V, V_{GS} = 0V$ $f = 1.0MHz$
Output Capacitance	C_{oss}	—	2.9	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	1.6	—	pF	
SWITCHING CHARACTERISTICS, $V_{GS} = 4.5V$ (Note 5)						
Turn-On Delay Time	$t_{d(on)}$	—	3.8	—	ns	$V_{GS} = 4.5V, V_{DD} = 10V$ $I_D = 200mA, R_G = 2.0\Omega$
Rise Time	t_r	—	7.9	—		
Turn-Off Delay Time	$t_{d(off)}$	—	13.4	—		
Fall Time	t_f	—	15.2	—		

- Notes:
- Short duration pulse test used to minimize self-heating effect.
 - Switching characteristics are independent of operating junction temperature.

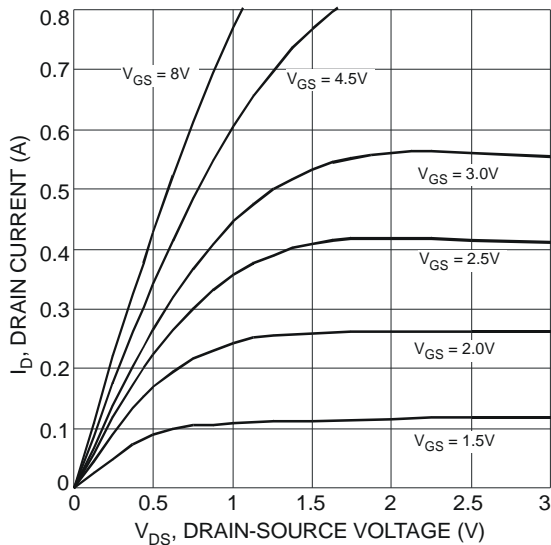


Fig. 1 Typical Output Characteristic

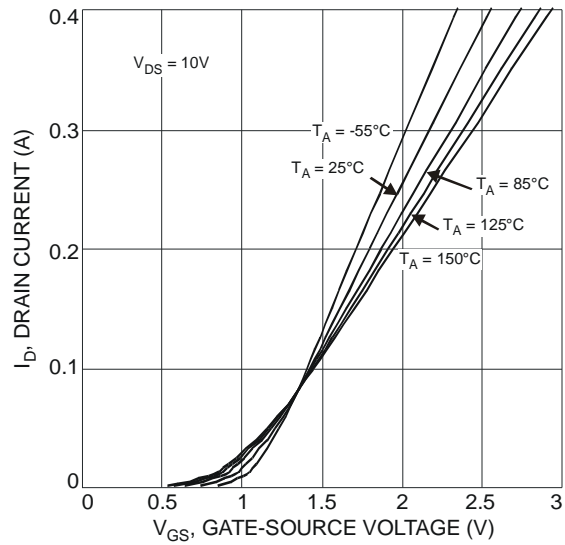


Fig. 2 Typical Transfer Characteristic

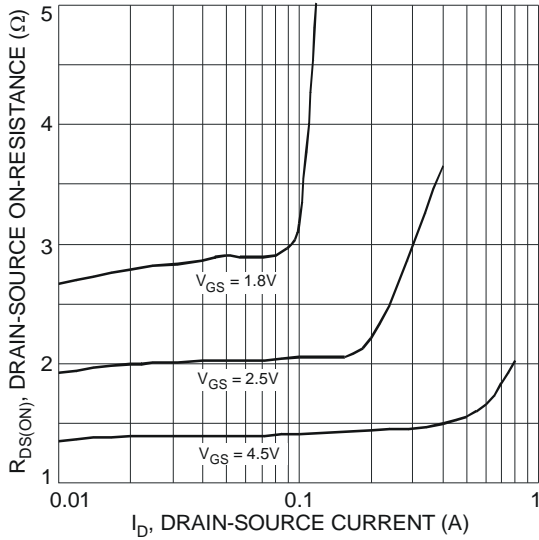


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

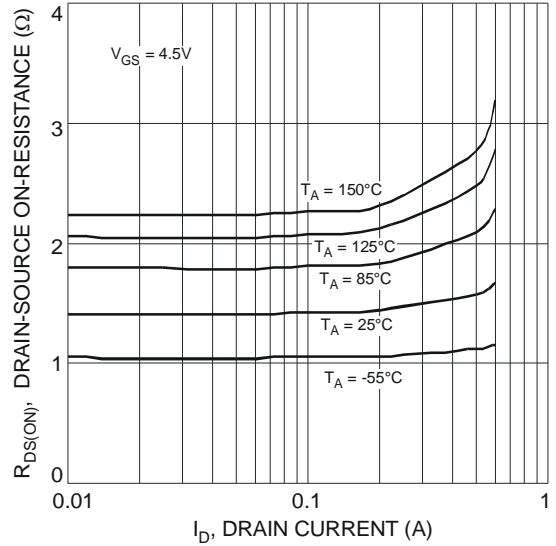


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

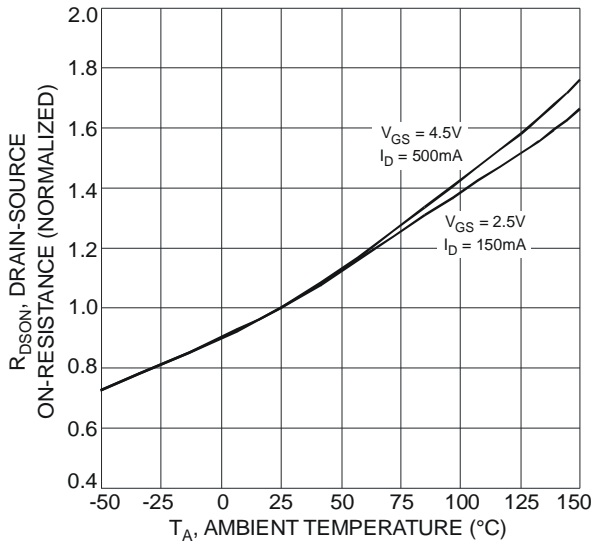


Fig. 5 On-Resistance Variation with Temperature

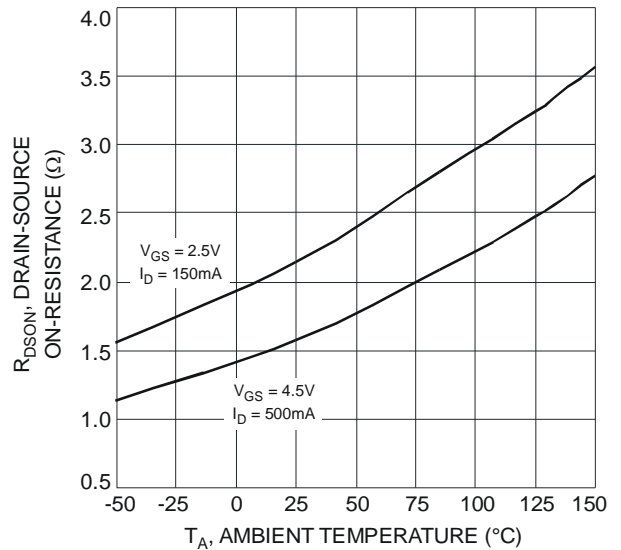


Fig. 6 On-Resistance Variation with Temperature

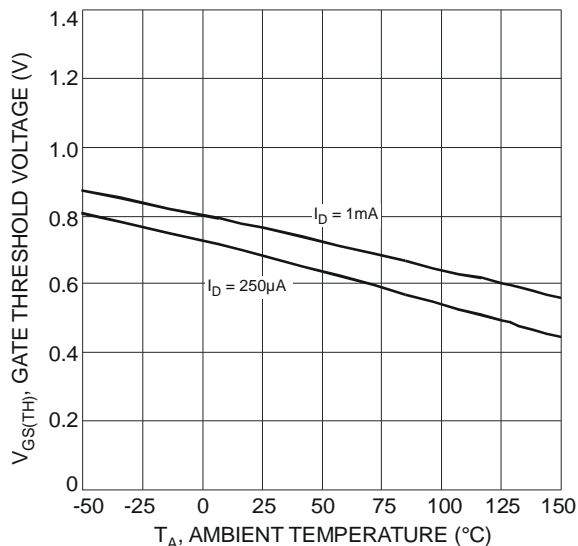


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

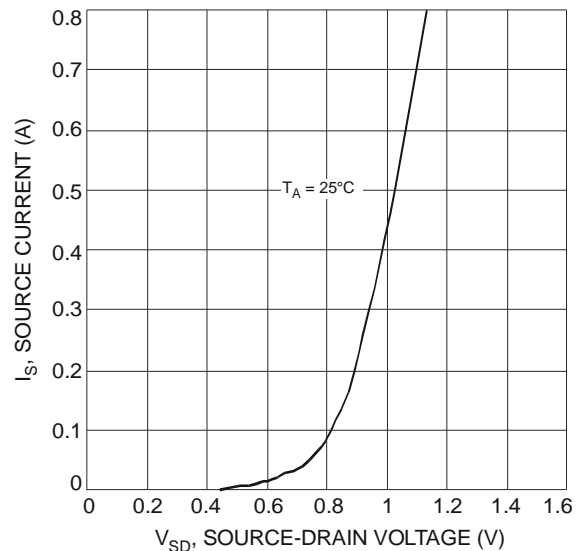


Fig. 8 Diode Forward Voltage vs. Current

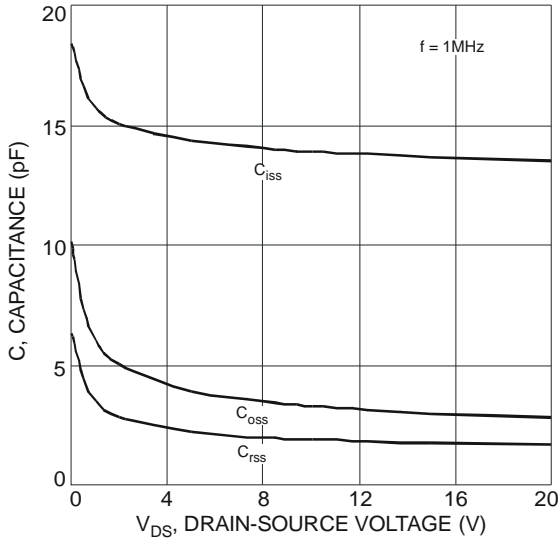


Fig. 9 Typical Total Capacitance

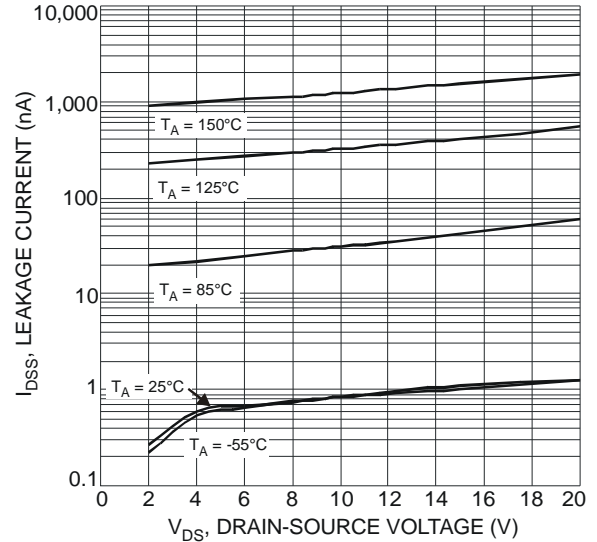


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

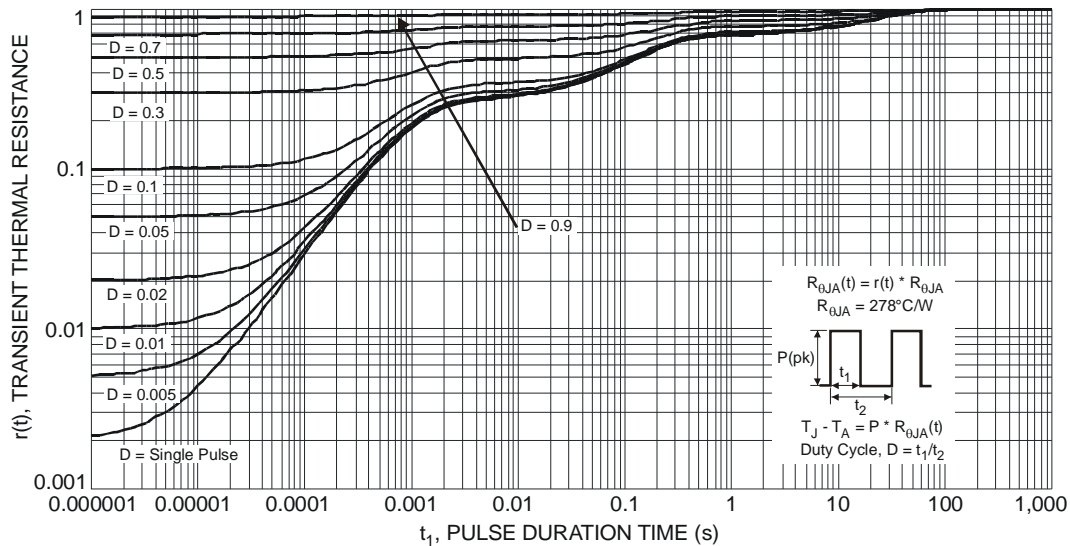


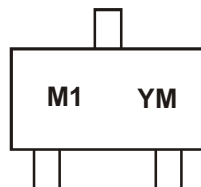
Fig. 11 Transient Thermal Response

Ordering Information (Note 6)

Part Number	Case	Packaging
DMN26D0UT-7	SOT-523	3,000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information

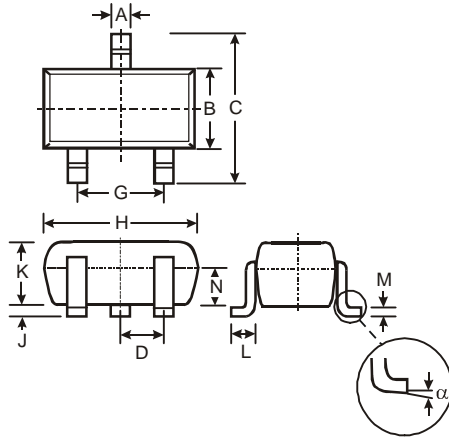


M1 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: W = 2009)
 M = Month (ex: 9 = September)

Date Code Key

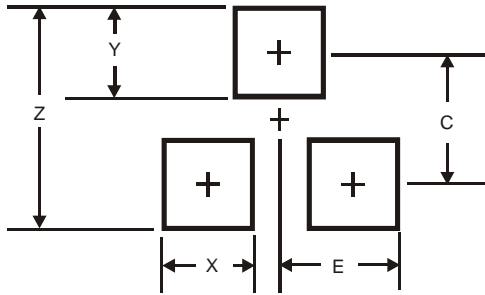
Year	2009	2010	2011	2012	2013	2014	2015					
Code	W	X	Y	Z	A	B	C					
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SOT-523			
Dim	Min	Max	Typ
A	0.15	0.30	0.22
B	0.75	0.85	0.80
C	1.45	1.75	1.60
D	—	—	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
J	0.00	0.10	0.05
K	0.60	0.80	0.75
L	0.10	0.30	0.22
M	0.10	0.20	0.12
N	0.45	0.65	0.50
α	0°	8°	—
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.8
X	0.4
Y	0.51
C	1.3
E	0.7

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Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9